

Rev.01 - 4 March 2019

**Product data sheet** 

#### 1. General description

Ultrafast power diode in a SOD142 (2-lead TO247) plastic package.

#### 2. Features and benefits

- · Fast switching and soft reverse recovery characteristics
- Low forward voltage drop
- Low leakage current
- Low reverse recovery current
- · Reduces switching losses in associated MOSFET or IGBT
- High operating temperature capability (T<sub>j (max)</sub> = 175°C)

### 3. Applications

- UPS
- EV Charger
- Welding Machine
- Air Conditioner

## 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions		Values		Unit	
Absolute	maximum rating						
$V_{\text{RRM}}$	repetitive peak reverse voltage			600			V
$I_{\rm F(AV)}$	average forward current	δ = 0.5 ; square-wave pulse; T <sub>mb</sub> ≤ 129 °C; Fig. 1; Fig. 2; Fig. 3		60		A	
I <sub>FRM</sub>	repetitive peak forward current	δ = 0.5 ; t <sub>p</sub> = 25 μs; T <sub>mb</sub> ≤ 129 °C; square-wave pulse		120		A	
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> = 10 ms; T <sub>j(init)</sub> = 25 °C; sine-wave pulse; <u>Fig. 4</u>	600		A		
		$t_{\rm p}$ = 8.3 ms; $T_{\rm j(init)}$ = 25 °C; sine-wave pulse;		660		А	
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static ch	aracteristics						
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 60 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>		-	1.55	2	V
		I <sub>F</sub> = 60 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>		-	1.2	1.6	V
Dynamic	characteristics						
t <sub>rr</sub>	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; \text{ d}I_F/\text{d}t = 50 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; \text{ Fig. 7}$		-	-	55	ns

# **5. Pinning information**

Table 2.	<b>Pinning info</b>	mation		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	К	cathode		K — A 001aaa020
2	А	anode		001888020
mb	mb	mounting base; connected to cathod	1 TO-247 (SOD142)	

# 6. Ordering information

Table 3. Ordering information								
Type number	Package	Orderable part number	Packing	Small packing	Package	Package		
	name		method	quantity	version	issue date		
BYV60W-600P	TO247	BYV60W-600PQ	Tube	30	SOD142	27-Nov-2012		

## 7. Marking

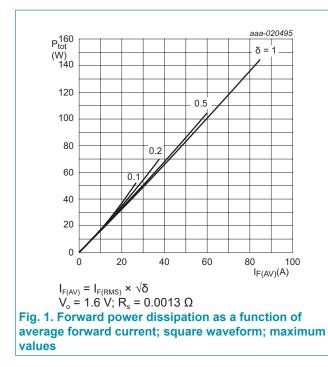
Table 4. Marking codes						
	Type number	Marking codes				
	BYV60W-600P	BYV60W-600P				

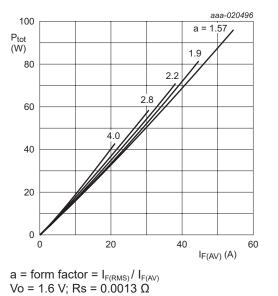
## 8. Limiting values

#### Table 5. Limiting values

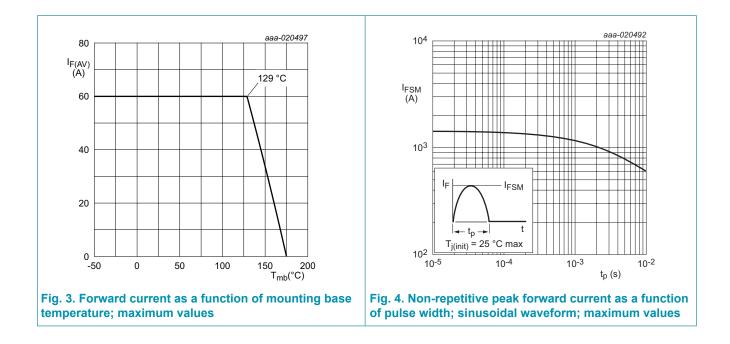
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V <sub>RRM</sub>	repetitive peak reverse voltage		600	V
V <sub>RWM</sub>	crest working reverse voltage		600	V
V <sub>R</sub>	reverse voltage	DC	600	V
I <sub>F(AV)</sub>	average forward current	δ = 0.5 ; square-wave pulse; T <sub>mb</sub> ≤ 129 °C; Fig. 1; Fig. 2; Fig. 3	60	A
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5 ; t <sub>p</sub> = 25 µs; T <sub>mb</sub> ≤ 129 °C; square-wave pulse	120	A
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	600	A
		$t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse;	660	А
l <sup>2</sup> t	limiting Joule-integral	SIN; t <sub>p</sub> = 10 ms	1800	A <sup>2</sup> s
T <sub>stg</sub>	storage temperature		-55 to 175	°C
Tj	junction temperature		175	°C



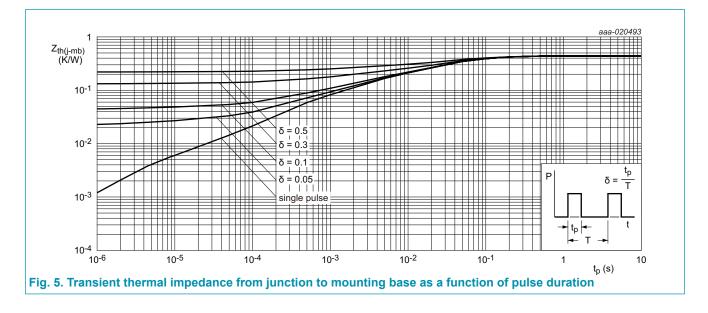


Vo = 1.6 V; Rs = 0.0013  $\Omega$ Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values



## 9. Thermal characteristics

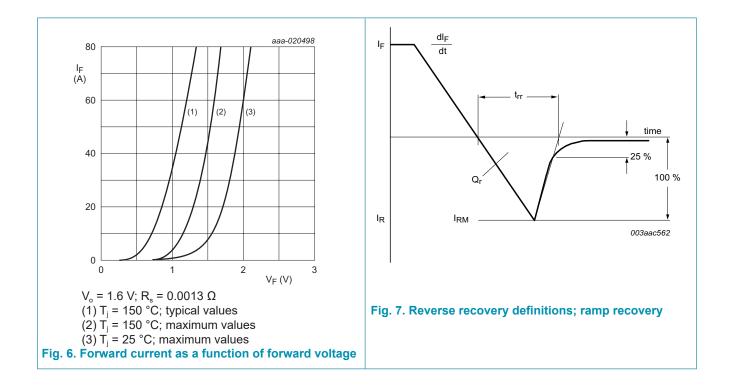
Table 6. Thermal characteristics								
Symbol	Parameter	Conditions		Min	Тур	Max	Unit	
$R_{\text{th(j-mb)}}$	thermal resistance from junction to mounting base	<u>Fig. 5</u>		-	-	0.44	K/W	
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air		-	45	-	K/W	



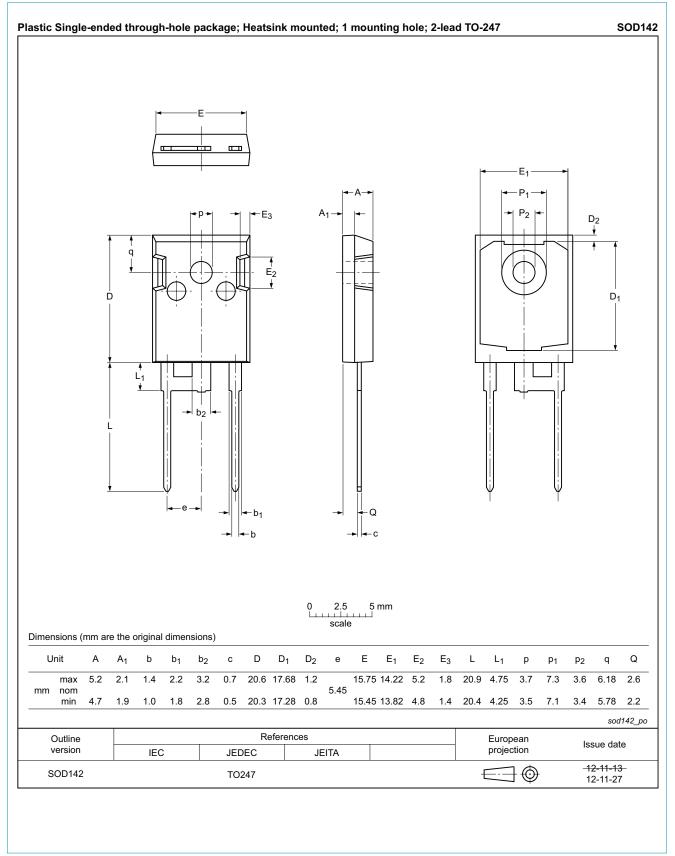
Ultrafast power diode

## **10. Characteristics**

Table 7. Cl	haracteristics					
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static ch	aracteristics					
V <sub>F</sub>	forward current	I <sub>F</sub> = 60 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>	-	1.55	2	V
		I <sub>F</sub> = 60 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>	-	1.2	1.6	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C	-	-	10	μA
		V <sub>R</sub> = 600 V; T <sub>j</sub> = 125 °C	-	-	500	μA
Dynamic	characteristics	· · · · ·				
Q <sub>r</sub>	reverse charge	$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	143	-	nC
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 7$	-	876	-	nC
t <sub>rr</sub>	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	-	55	ns
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	53	-	ns
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 7$	-	120	-	ns
I <sub>RM</sub>	peak reverse recovery current	$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	5.4	-	A
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 7$	-	14.5	-	A
E <sub>as</sub>	non-repetitive avalanche energy	I <sub>R</sub> = 2.2 A; T <sub>j(init)</sub> = 25 °C; L = 40 mH	-	97	-	mJ



### **11. Package outline**



# BYV60W-600P

#### Ultrafast power diode

## 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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